

Specifications

Insulation Resistance



SMD Comm COG Flex, Ceramic, 47 pF, 5%, 50 VDC, COG, SMD, MLCC, FTCAP, Ultra-Stable, 0603, 0.4 mm



General Information	
Series	SMD Comm COG Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Capacitance	4/ pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

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